ABSTRACT

**REMOVING PARTICLES BY ADHESIVE METHOD**

The removal of particulate contaminants, such as dust particles, from the surface of a semiconductor wafer is achieved by pressing a soft adhesive layer against the wafer surface, leaving it in place for a short time and then removing it. The adhesive is brought to the wafer surface on a flexible medium which serves as a backing layer and to whose other side pressure can be applied. To remove the adhesive, the backing layer is peeled off, either by pulling on one end or by passing a sticky roller over it. The operation may be performed in air or under vacuum.

(FIGURE 1 IS SUGGESTED FOR PUBLICATION)